

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Vinay Nair	05/23/2013
Lars Heineck	05/24/2013
RECEIVING PARTY DATA	
Name:	NANYA TECHNOLOGY CORP.
Street Address:	Hwa-Ya Technology Park 669, Fuhsing 3 Rd., Kueishan
City:	Tao-Yuan Hsien
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13974032
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	NTCP0520USA
NAME OF SUBMITTER:	KATE YEH
Signature:	/KATE YEH/
Date:	08/22/2013
Total Attachments: 4 source=1730830#page1.tif source=1730830#page2.tif source=1730830#page3.tif source=1730830#page4.tif	

CH \$40.00 13974032

PATENT

Docket No NTCP0520USA

**ASSIGNMENT OF INVENTION**

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

**ASSIGNOR(S) (Inventors):**

Name: Vinay Nair Nationality: IN

Name: Lars Heineck Nationality: DE

Hereby sells, assigns and transfers to

**ASSIGNEE(S):**

Name: NANYA TECHNOLOGY CORP.

Address: Hwa-Ya Technology Park 669, Fuhsing 3 Rd., Kueishan, Tao-Yuan Hsien, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"METHOD FOR SEMICONDUCTOR CROSS PITCH DOUBLED PATTERNING PROCESS"

Which is found in :

- (a) + U.S. patent application executed on even date
- (b) \_\_\_\_\_ U.S. patent application executed on \_\_\_\_\_
- (c) \_\_\_\_\_ U.S. application serial no. \_\_\_\_\_
- (d) \_\_\_\_\_ patent no. \_\_\_\_\_ issued \_\_\_\_\_
- (e) \_\_\_\_\_ International application no. \_\_\_\_\_

PATENT

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

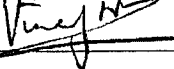
IN WITNESS WHEREOF, We have hereunto set hand and seal this 5/23/2013 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Vinay Nair

Lars Heineck

Signature of INVENTOR



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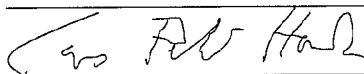
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(Type name of inventor)

**Signature of INVENTOR**

Vinay Nair

Lars Heineck



05/24/2013